25th International Conference on Electronic Packaging Technology

August 7 to 9, 2024, Tianjin, China

http://www.icept.org

Course subject：

The Heterogeneous Integration Package Development Trend

Course leader：Scott Chen—Sr. VP of Central Developing Engineering ASE Group, Chung-Li

Speech Description/Objective:

The technology types and development trends in packaging

Introduction to advanced packaging technology

System level heterogeneous integration module technology scheme

Introduction of Speaker：

Scott Chen is Senior Vice President of Central Development Engineering at ASE Chung-Li branch (Advance Semiconductor Engineering) currently, responsible for semiconductor packaging R&D.

He has been working on semiconductor Packaging technology more than 30 years, experienced most of the assembly technology, including cu wire bonding, MEMS and optical sensor, bumping & flip chip, advanced packaging and system in package technology. Not only technology, but also operation experience.

During 2013 and 2014, Scott is also the vice chairman of MEMS committee in Semi-Taiwan Industry Association. He has been the invited Speaker for many Forum and Summit, ex. Semicon West, Semicon Taiwan, IMPACT, ECTC and ICEPT.

He graduated from Department on Chemical Engineering in Taiwan National University, and also granted the EMBA Master degree.